

Title (en)  
ELECTRONIC SYSTEM COMPRISING A LOWER REDISTRIBUTION LAYER AND METHOD FOR PRODUCING SUCH AN ELECTRONIC SYSTEM

Title (de)  
ELEKTRONISCHES SYSTEM MIT EINER UNTEREN UMVERTEILUNGSSCHICHT UND VERFAHREN ZUR HERSTELLUNG EINES SOLCHEN ELEKTRONISCHEN SYSTEMS

Title (fr)  
SYSTÈME ÉLECTRONIQUE COMPRENANT UNE COUCHE DE REDISTRIBUTION INFÉRIEURE ET PROCÉDÉ DE FABRICATION D'UN TEL SYSTÈME ÉLECTRONIQUE

Publication  
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Application  
**EP 18748943 A 20180808**

Priority  
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Abstract (en)  
[origin: WO2019030288A1] The invention relates to a method for producing an electronic system (S), comprising: - a step of forming a plurality of interconnect paths obtained via metal deposition on the sacrificial member (2) to form a lower redistribution layer (7) defining a plurality of lower connection ports (71) connected to a plurality of inner connection ports (72), - a step of depositing at least one electronic component (3) on the lower redistribution layer (7), and - a step of forming a plurality of three-dimensional interconnect paths obtained via metal deposition in order to connect the connectors (30) of the electronic component (3) to the inner connection ports (72) of the lower redistribution layer (7).

IPC 8 full level  
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CPC (source: EP US)  
**H01L 21/4853** (2013.01 - US); **H01L 21/4857** (2013.01 - US); **H01L 21/4867** (2013.01 - EP); **H01L 21/561** (2013.01 - EP); **H01L 21/565** (2013.01 - US); **H01L 21/568** (2013.01 - EP US); **H01L 21/6835** (2013.01 - EP US); **H01L 23/3128** (2013.01 - US); **H01L 23/5383** (2013.01 - US); **H01L 23/5386** (2013.01 - US); **H01L 23/5389** (2013.01 - EP US); **H01L 24/19** (2013.01 - US); **H01L 24/20** (2013.01 - US); **H01L 24/24** (2013.01 - EP); **H01L 24/82** (2013.01 - EP); **H01L 25/0652** (2013.01 - EP); **H01L 25/18** (2013.01 - EP); **H01L 25/50** (2013.01 - EP); **H01L 23/49816** (2013.01 - EP); **H01L 2221/68345** (2013.01 - EP); **H01L 2221/68372** (2013.01 - EP US); **H01L 2224/214** (2013.01 - US); **H01L 2224/24145** (2013.01 - EP); **H01L 2224/24195** (2013.01 - EP); **H01L 2224/24225** (2013.01 - EP); **H01L 2224/32145** (2013.01 - EP); **H01L 2224/82001** (2013.01 - EP); **H01L 2924/15311** (2013.01 - EP); **H01L 2924/1815** (2013.01 - EP); **H01L 2924/19105** (2013.01 - EP); **H01L 2924/3025** (2013.01 - EP)

Citation (search report)  
See references of WO 2019030288A1

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DOCDB simple family (publication)  
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